



L Number	Hits	Search Text	DB	Time stamp
-	766	laser and (pulse with picosecond)	USPAT;	2003/03/25
			US-PGPUB	15:52
-	826820	cutting or cut or dice ordiced or dicing	USPAT;	2003/03/25
			US-PGPUB	15:15
-	63450	438/\$.ccls.	USPAT;	2003/03/25
			US-PGPUB	15:15
-	6	(laser and (pulse with picosecond)) and (cutting or cut or dice	USPAT;	2003/03/25
		ordiced or dicing) and 438/\$.ccls.	US-PGPUB	15:51
-	2	(laser and (pulse with picosecond)) with (cutting or cut or dice	USPAT;	2003/03/25
		or diced or dicing)	US-PGPUB	15:53
-	224	(laser and (pulse with picosecond)) and (cutting or cut or dice	USPAT;	2003/03/25
		ordiced or dicing)	US-PGPUB	15:56
-	309554	@ad>20010221 or @rlad>20010221	USPAT;	2003/03/25
			US-PGPUB	15:56
-	182	((laser and (pulse with picosecond)) and (cutting or cut or dice	USPAT;	2003/03/25
		ordiced or dicing)) not (@ad>20010221 or @rlad>20010221)	US-PGPUB	16:04
-	33921	(cutting or cut or dice ordiced or dicing) with (substrate or	USPAT;	2003/03/25
		wafer)	US-PGPUB	16:05
-	15	(((laser and (pulse with picosecond)) and (cutting or cut or	USPAT;	2003/03/25
		dice ordiced or dicing)) not (@ad>20010221 or	US-PGPUB	16:05
		@riad>20010221)) and ((cutting or cut or dice ordiced or		1
		dicing) with (substrate or wafer))		